#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

C. Huang

U.S.S.N.:

Not Yet Assigned [Divisional of U.S. Serial No. 09/908,236]

FILED:

Herewith

FOR:

SEMICONDUCTOR PACKAGE AND FABRICATING METHOD

**THEREOF** 

### **CERTIFICATE OF EXPRESS MAILING**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on this date <u>July 25, 2003</u> in an envelope as "Express Mail Post Office to Addressee," mailing Label Number <u>EV343734470US</u> addressed to the: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

By: Michelle P. Chicos

Commissioner for Patents

P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

## PRELIMINARY AMENDMENT

Applicant kindly requests that the above-identified application be amended as follows:

## IN THE SPECIFICATION

Please add the following on page 1 after the title:

# CROSS-REFERENCE TO RELATED APPLICATION(S)

This application is a divisional of copending application U.S. Serial No. 09/908,236, filed on July 18, 2001.